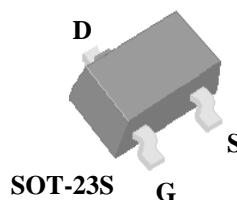
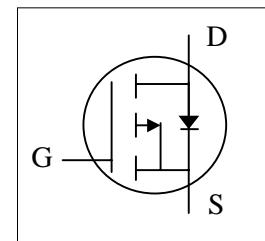




- ▼ Capable of 2.5V Gate Drive
- ▼ Small Package Outline
- ▼ Surface Mount Device
- ▼ RoHS Compliant & Halogen-Free



BV_{DSS}	-20V
$R_{DS(ON)}$	160mΩ
I_D	-2.5A



Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, low on-resistance and cost-effectiveness.

The SOT-23S package is widely preferred for commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters.

Absolute Maximum Ratings@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 12	V
$I_D @ T_A=25^\circ\text{C}$	Drain Current ³ , $V_{GS} @ 4.5\text{V}$	-2.5	A
$I_D @ T_A=70^\circ\text{C}$	Drain Current ³ , $V_{GS} @ 4.5\text{V}$	-1.97	A
I_{DM}	Pulsed Drain Current ¹	-10	A
$P_D @ T_A=25^\circ\text{C}$	Total Power Dissipation	0.83	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Value	Unit
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient ³	150	°C/W



Electrical Characteristics@ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=-250\mu\text{A}$	-20	-	-	V
$R_{\text{DS(ON)}}$	Static Drain-Source On-Resistance ²	$V_{\text{GS}}=-10\text{V}, I_{\text{D}}=-2.8\text{A}$	-	-	120	$\text{m}\Omega$
		$V_{\text{GS}}=-4.5\text{V}, I_{\text{D}}=-2.5\text{A}$	-	-	160	$\text{m}\Omega$
		$V_{\text{GS}}=-2.5\text{V}, I_{\text{D}}=-2\text{A}$	-	-	300	$\text{m}\Omega$
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=-250\mu\text{A}$	-0.4	-	-1.2	V
g_{fs}	Forward Transconductance	$V_{\text{DS}}=-5\text{V}, I_{\text{D}}=-2\text{A}$	-	4	-	S
I_{DSS}	Drain-Source Leakage Current	$V_{\text{DS}}=-20\text{V}, V_{\text{GS}}=0\text{V}$	-	-	-1	uA
I_{GSS}	Gate-Source Leakage	$V_{\text{GS}}=\pm 12\text{V}, V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
Q_g	Total Gate Charge	$I_{\text{D}}=-2\text{A}$	-	5	8	nC
Q_{gs}	Gate-Source Charge	$V_{\text{DS}}=-16\text{V}$	-	1	-	nC
Q_{gd}	Gate-Drain ("Miller") Charge	$V_{\text{GS}}=-4.5\text{V}$	-	2	-	nC
$t_{\text{d(on)}}$	Turn-on Delay Time	$V_{\text{DS}}=-10\text{V}$	-	6	-	ns
t_r	Rise Time	$I_{\text{D}}=-1\text{A}$	-	17	-	ns
$t_{\text{d(off)}}$	Turn-off Delay Time	$R_G=3.3\Omega$	-	16	-	ns
t_f	Fall Time	$V_{\text{GS}}=-10\text{V}$	-	5	-	ns
C_{iss}	Input Capacitance	$V_{\text{GS}}=0\text{V}$	-	270	430	pF
C_{oss}	Output Capacitance	$V_{\text{DS}}=-20\text{V}$	-	70	-	pF
C_{rss}	Reverse Transfer Capacitance	f=1.0MHz	-	55	-	pF

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V_{SD}	Forward On Voltage ²	$I_{\text{S}}=-1.2\text{A}, V_{\text{GS}}=0\text{V}$	-	-	-1.2	V
t_{rr}	Reverse Recovery Time	$I_{\text{S}}=-2\text{A}, V_{\text{GS}}=0\text{V},$ $dI/dt=100\text{A}/\mu\text{s}$	-	20	-	ns
Q_{rr}	Reverse Recovery Charge		-	15	-	nC

Notes:

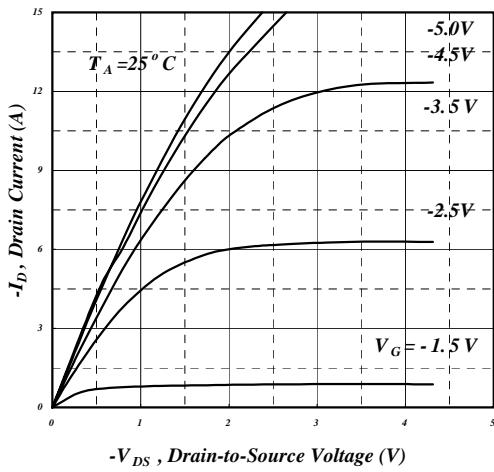
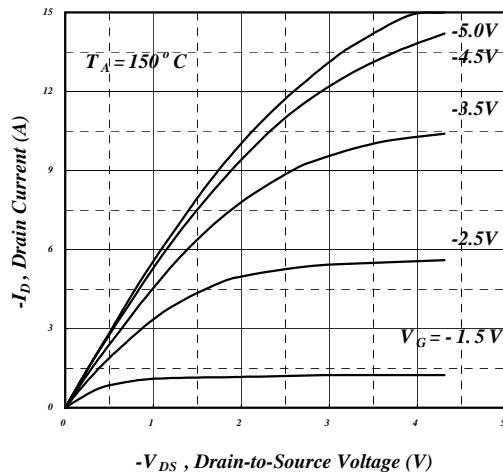
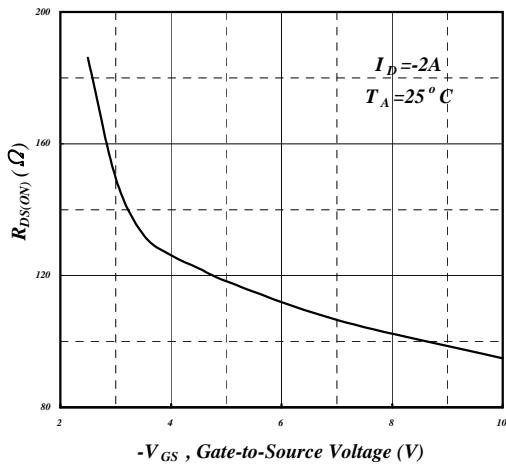
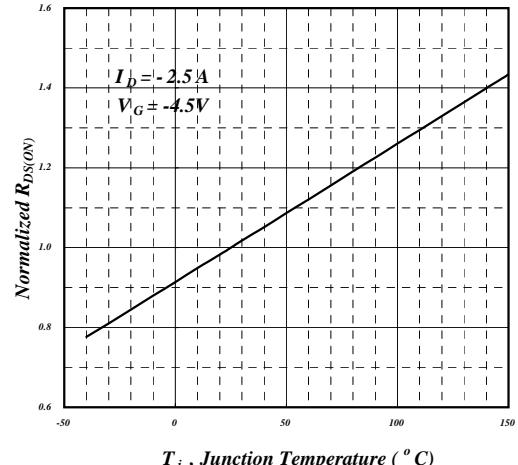
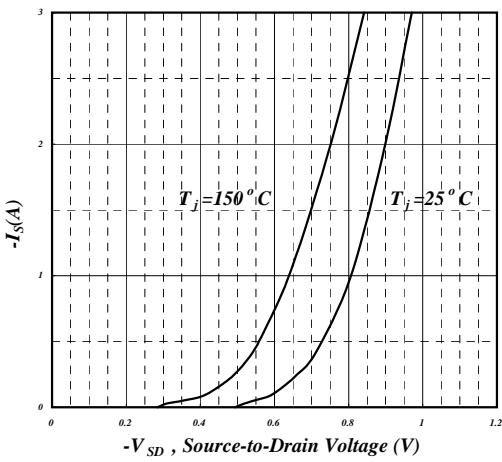
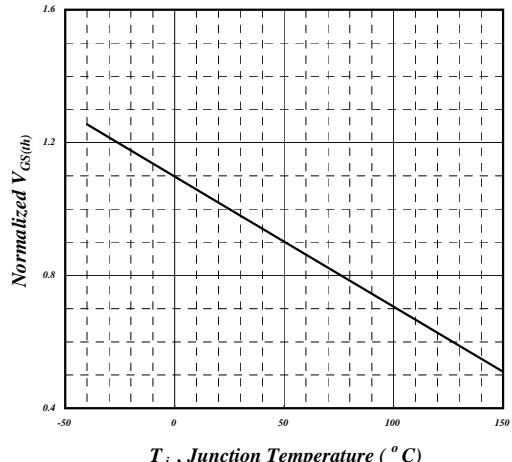
- 1.Pulse width limited by Max. junction temperature.
- 2.Pulse test
- 3.Surface mounted on 1 in² copper pad of FR4 board, t \leq 10sec ; 360 °C/W when mounted on Min. copper pad.

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

APEC RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.


Fig 1. Typical Output Characteristics

Fig 2. Typical Output Characteristics

Fig 3. On-Resistance v.s. Gate Voltage

Fig 4. Normalized On-Resistance v.s. Junction Temperature

Fig 5. Forward Characteristic of Reverse Diode

Fig 6. Gate Threshold Voltage v.s. Junction Temperature

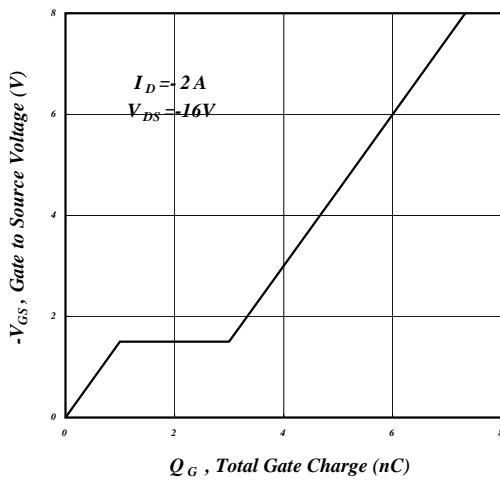


Fig 7. Gate Charge Characteristics

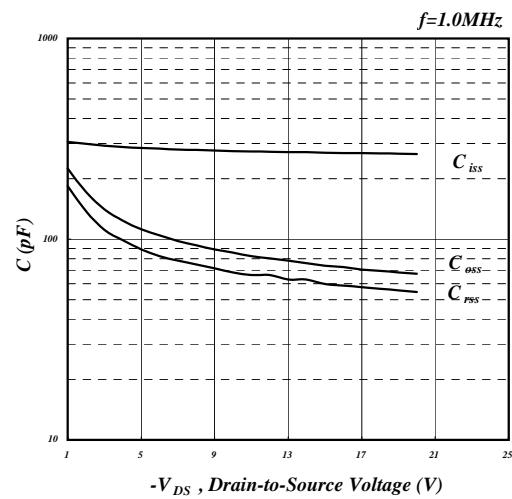


Fig 8. Typical Capacitance Characteristics

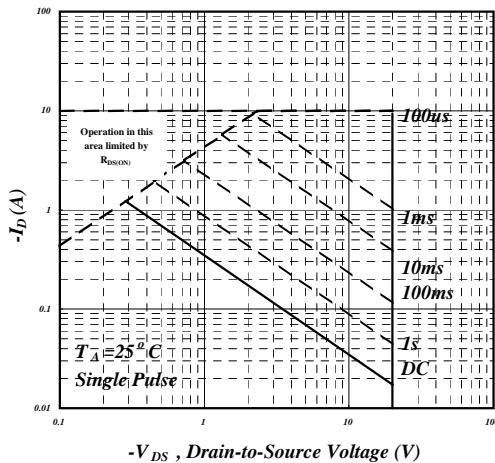


Fig 9. Maximum Safe Operating Area

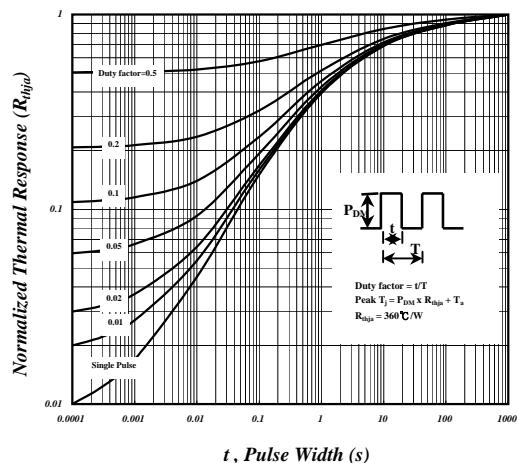


Fig 10. Effective Transient Thermal Impedance

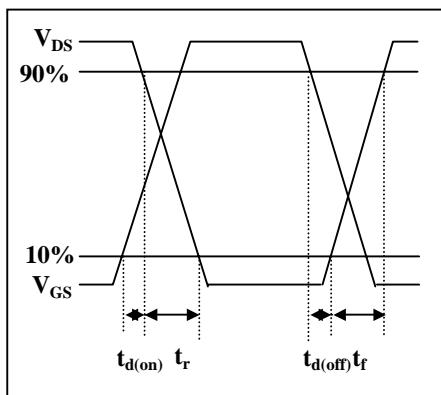


Fig 11. Switching Time Waveform

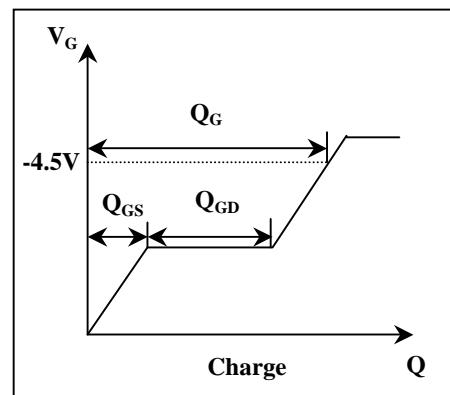
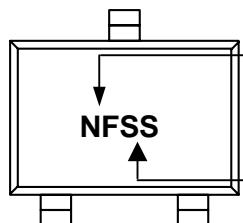


Fig 12. Gate Charge Waveform



AP2313GN

MARKING INFORMATION



Part Number : NF

Date Code : SS

SS:2004,2008,2012...

SS:2003,2007,2011...

SS:2002,2006,2010...

SS:2001,2005,2009...